

a substrate having a plurality of pockets disposed therein and a plurality of metallic contact pads distributed thereon and approximately aligned with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and

an anisotropically conductive layer disposed between and mechanically coupled to the bumped device and to the substrate, the anisotropically conductive layer electrically coupling each of the conductive bumps with a corresponding one of the contact pads.

9. (Twice Amended) An apparatus for testing a bumped device having a plurality of conductive bumps, comprising:

a substrate including a first surface having a plurality of pockets disposed therein and a plurality of metallic contact pads distributed thereon, the contact pads being substantially alignable with the plurality of conductive bumps, each contact pad being at least partially disposed within one of the pockets; and

an anisotropically conductive layer disposed on the first surface and engageable with the plurality of conductive bumps to electrically couple each of the conductive bumps with a corresponding one of the contact pads.

#### REMARKS

Claims 1, 3, 5-12 and 15-17 are currently pending in this continuation application. In the Office Action dated September 10, 2002, the Examiner withdrew from consideration claims 15-17. Claims 15-17 are hereby canceled without prejudice to the filing of any divisional, continuation, or continuation-in-part application. The Examiner further rejected claims 1, 3 and 5-12 under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,137,183 to Sako. Applicants disagree with this ground of rejection and wish to clarify various distinctions of Applicants' invention over the prior art. Applicants respectfully request reconsideration of the application in view of the foregoing amendments and the following remarks.

The disclosed embodiments of the invention will now be discussed in comparison to the prior art. Of course, the discussion of the disclosed embodiments, and the discussion of